

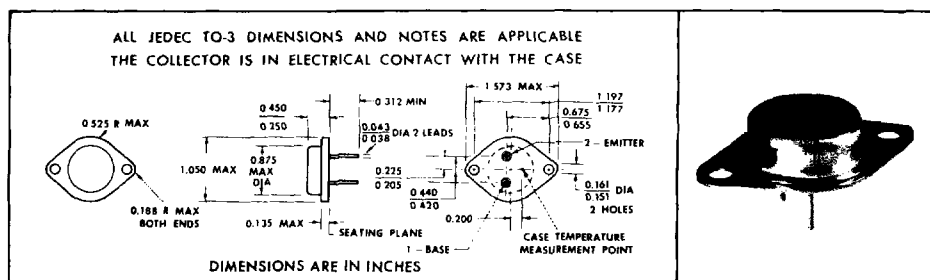
TYPES 2N3789, 2N3790, 2N3791, 2N3792 P-N-P SINGLE-DIFFUSED SILICON POWER TRANSISTORS

FOR POWER-AMPLIFIER AND HIGH-SPEED-SWITCHING APPLICATIONS
DESIGNED FOR COMPLEMENTARY USE WITH 2N3713 THRU 2N3716

- 150 Watts at 25°C Case Temperature
- 10 A Rated Collector Current
- Min f_T of 4 MHz at 10 V, 500 mA
- Min f_{hfe} of 30 kHz at 10 V, 500 mA

TYPES 2N3789, 2N3790, 2N3791, 2N3792
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***mechanical data**



absolute maximum ratings at 25°C case temperature (unless otherwise noted)

	2N3789	2N3790
*Collector-Base Voltage	2N3791	2N3792
	-60 V	-80 V
*Collector-Emitter Voltage (See Note 1)	-60 V	-80 V
*Emitter-Base Voltage	← -7 V →	
*Continuous Collector Current	← -10 A →	
Peak Collector Current (See Note 2)	← -15 A →	
*Continuous Base Current	← -4 A →	
*Safe Operating Region at (or below) 25°C Case Temperature	See Figures 6 and 7	
*Continuous Device Dissipation at (or below) 25°C Case Temperature (See Note 3)	← 150 W →	
Continuous Device Dissipation at (or below) 25°C Free-Air Temperature (See Note 4)	← 4 W →	
*Operating Collector Junction Temperature Range	-65°C to 200°C	
*Storage Temperature Range	-65°C to 200°C	
Lead Temperature 1/16 Inch from Case for 10 Seconds	← 235°C →	

- NOTES: 1. This value applies when the base-emitter diode is open-circuited.
2. This value applies for $t_p = 0.3$ ms, duty cycle $\leq 10\%$.
3. Derate linearly to 200°C case temperature at the rate of 0.855 W/deg.
4. Derate linearly to 200°C free-air temperature at the rate of 22.9 mW/deg.

*Indicates JEDEC registered data

TYPES 2N3789, 2N3790, 2N3791, 2N3792

P-N-P SINGLE-DIFFUSED SILICON POWER TRANSISTORS

*electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	2N3789	2N3790	2N3791	2N3792	UNIT
		MIN MAX	MIN MAX	MIN MAX	MIN MAX	
$V_{(BR)CEO}$ Collector-Emitter Breakdown Voltage	$I_C = -200$ mA, $I_B = 0$, See Note 5	-60	-80	-60	-80	V
I_{CEO} Collector Cutoff Current	$V_{CE} = -30$ V, $I_B = 0$	-10		-10		mA
	$V_{CE} = -40$ V, $I_B = 0$		-10		-10	
I_{CEV} Collector Cutoff Current	$V_{CE} = -60$ V, $V_{BE} = 1.5$ V	-1		-1		mA
	$V_{CE} = -80$ V, $V_{BE} = 1.5$ V		-1		-1	
	$V_{CE} = -60$ V, $V_{BE} = 1.5$ V, $T_C = 150^\circ\text{C}$	-5		-5		
	$V_{CE} = -80$ V, $V_{BE} = 1.5$ V, $T_C = 150^\circ\text{C}$		-5		-5	
I_{EBO} Emitter Cutoff Current	$V_{EB} = -7$ V, $I_C = 0$	-5	-5	-5	-5	mA
h_{FE} Static Forward Current Transfer Ratio	$V_{CE} = -2$ V, $I_C = -1$ A, See Notes 5 and 6	25 90	25 90	50 180	50 180	
	$V_{CE} = -2$ V, $I_C = -3$ A, See Notes 5 and 6	15	15	30	30	
	$V_{CE} = -4$ V, $I_C = -10$ A, See Notes 5 and 6	4	4	4	4	
V_{BE} Base-Emitter Voltage	$V_{CE} = -2$ V, $I_C = -5$ A, See Notes 5 and 6	-2	-2	-1.8	-1.8	V
	$V_{CE} = -4$ V, $I_C = -10$ A, See Notes 5 and 6	-4	-4	-4	-4	
$V_{CE(sat)}$ Collector-Emitter Saturation Voltage	$I_B = -0.4$ A, $I_C = -4$ A, See Notes 5 and 6	-1	-1			V
	$I_B = -0.5$ A, $I_C = -5$ A, See Notes 5 and 6			-1	-1	
	$I_B = -2$ A, $I_C = -10$ A, See Notes 5 and 6	-4	-4	-4	-4	
h_{fe} Small-Signal Common-Emitter Forward Current Transfer Ratio	$V_{CE} = -10$ V, $I_C = -0.5$ A, $f = 1$ kHz	25 250	25 250	25 250	25 250	
$ h_{fe} $ Small-Signal Common-Emitter Forward Current Transfer Ratio	$V_{CE} = -10$ V, $I_C = -0.5$ A, $f = 1$ MHz	4	4	4	4	
f_{hfe} Small-Signal Common-Emitter Forward Current Transfer Ratio Cutoff Frequency	$V_{CE} = -10$ V, $I_C = -0.5$ A, See Note 7	30	30	30	30	kHz
C_{obo} Common-Base Open-Circuit Output Capacitance	$V_{CB} = -10$ V, $I_E = 0$, $f = 100$ kHz	500	500	500	500	pF

NOTES: 5. These parameters must be measured using pulse techniques. $t_p = 300$ μ s, duty cycle $\leq 2\%$.

6. These parameters are measured with voltage-sensing contacts separate from the current-carrying contacts.

7. f_{hfe} is the frequency at which the magnitude of the small-signal forward current transfer ratio is 0.707 of its low-frequency value. For this device, the reference measurement is made at 1 kHz.

*Indicates JEDEC registered data

thermal characteristics

PARAMETER	MAX	UNIT
θ_{J-C} Junction-to-Case Thermal Resistance	1.17	deg/W
θ_{J-A} Junction-to-Free-Air Thermal Resistance	43.7	

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switching characteristics at 25°C case temperature

PARAMETER	TEST CONDITIONS†	TYP	UNIT
t_{on} Turn-On Time	$I_C = -1 \text{ A}$, $I_{B(1)} = -100 \text{ mA}$, $I_{B(2)} = 100 \text{ mA}$,	0.35	μs
t_{off} Turn-Off Time	$V_{BE(off)} = 3.7 \text{ V}$, $R_L = 20 \Omega$, See Figure 1	0.8	

† Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

PARAMETER MEASUREMENT INFORMATION

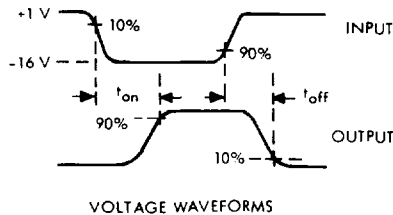
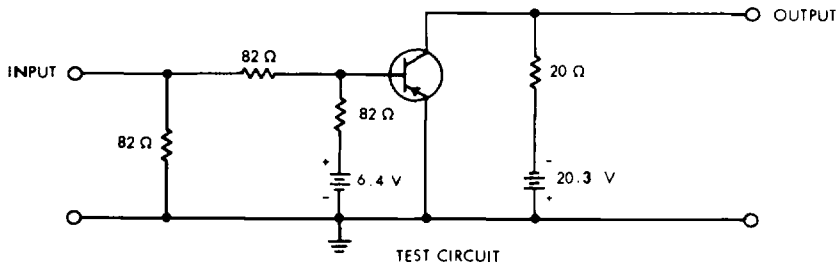


FIGURE 1

- NOTES: a. The input waveform is supplied by a generator with the following characteristics: $t_r \leq 15 \text{ ns}$, $t_f \leq 15 \text{ ns}$, $Z_{out} = 50 \Omega$, $t_p = 10 \mu\text{s}$, duty cycle $\leq 2\%$.
- b. Waveforms are monitored on an oscilloscope with the following characteristics: $t_r \leq 15 \text{ ns}$, $R_{in} \geq 10 \text{ M}\Omega$, $C_{in} \leq 11.5 \text{ pF}$.
- c. Resistors must be noninductive types.
- d. The d-c power supplies may require additional bypassing in order to minimize ringing.

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TYPICAL CHARACTERISTICS

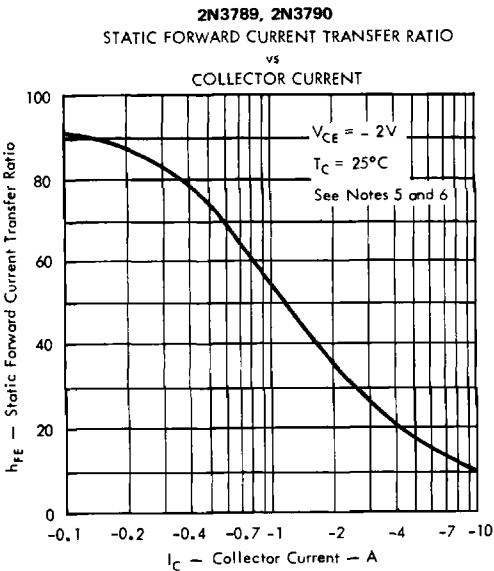


FIGURE 2

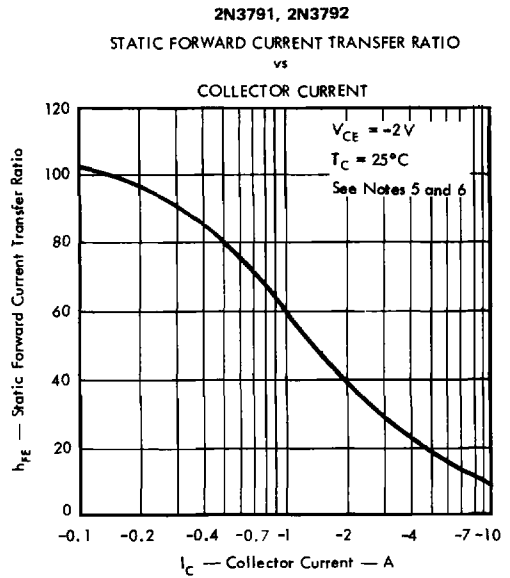


FIGURE 3

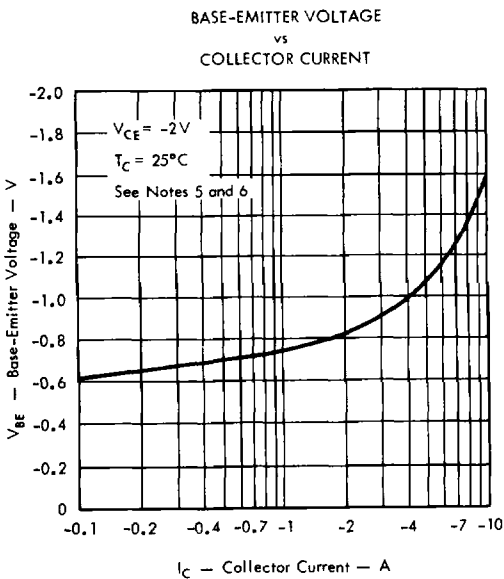


FIGURE 4

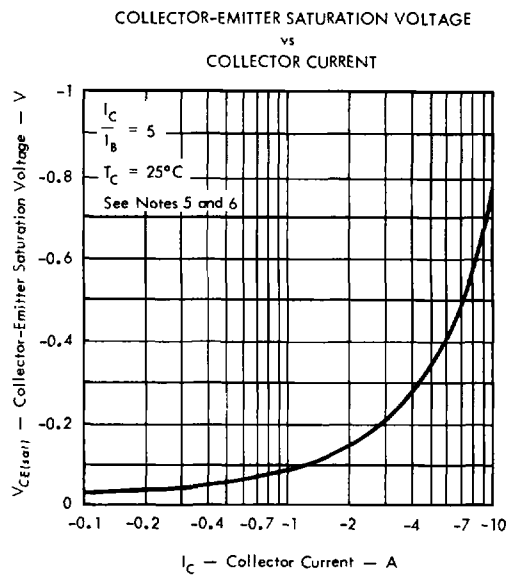


FIGURE 5

NOTES: 5. These parameters must be measured using pulse techniques. $t_p = 300 \mu s$, duty cycle $\leq 2\%$.

6. These parameters are measured with voltage-sensing contacts separate from the current-carrying contacts.

TYPES 2N3789, 2N3790, 2N3791, 2N3792

P-N-P SINGLE-DIFFUSED SILICON POWER TRANSISTORS

MAXIMUM SAFE OPERATING REGIONS

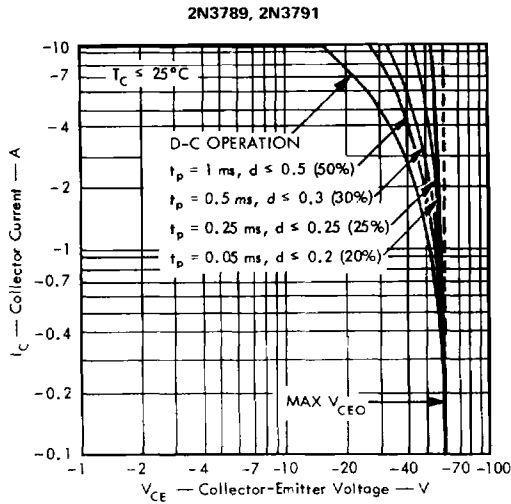


FIGURE 6

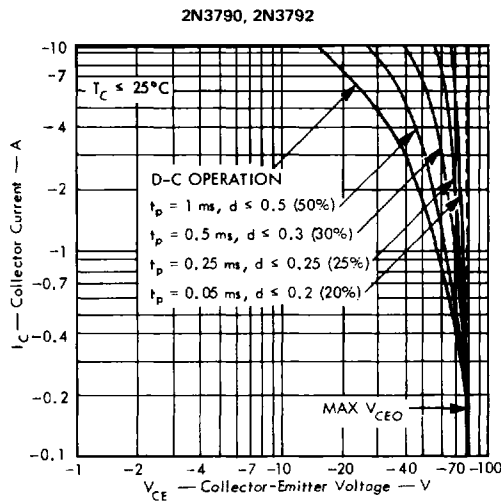


FIGURE 7

TYPES 2N3789, 2N3790, 2N3791, 2N3792 P-N-P SINGLE-DIFFUSED SILICON POWER TRANSISTORS

THERMAL INFORMATION

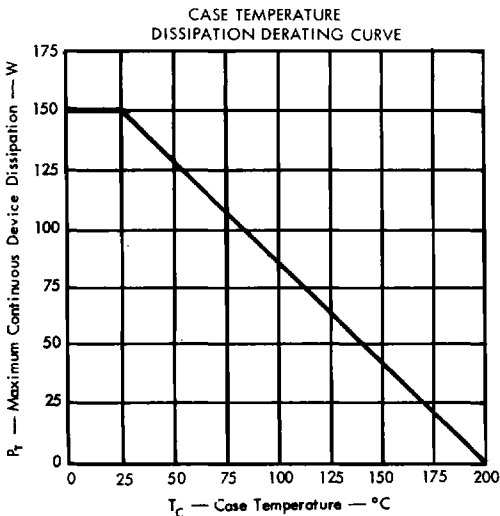


FIGURE 8

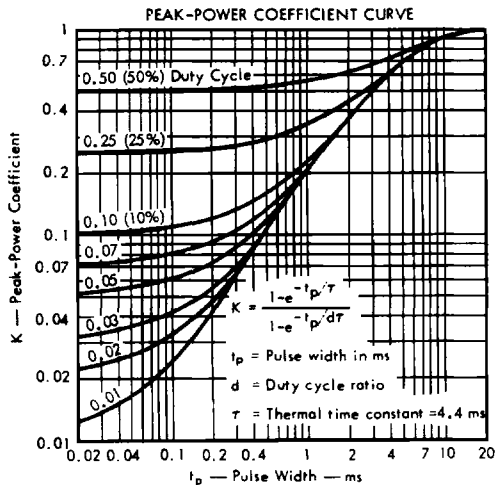


FIGURE 9

SYMBOL DEFINITION

SYMBOL	DEFINITION	VALUE	UNIT
$P_{T(av)}$	Average Power Dissipation		W
$P_{T(max)}$	Peak Power Dissipation		W
θ_{J-A}	Junction-to-Free-Air Thermal Resistance	43.7	deg/W
θ_{J-C}	Junction-to-Case Thermal Resistance	1.17	deg/W
θ_{C-A}	Case-to-Free-Air Thermal Resistance	42.5	deg/W
θ_{C-HS}	Case-to-Heat-Sink Thermal Resistance		deg/W
θ_{HS-A}	Heat-Sink-to-Free-Air Thermal Resistance		deg/W
T_A	Free-Air Temperature		°C
T_C	Case Temperature		°C
$T_{J(av)}$	Average Junction Temperature	≤ 200	°C
$T_{J(max)}$	Peak Junction Temperature	≤ 200	°C
K	Peak-Power Coefficient	See Figure 9	
t_p	Pulse Width		ms
t_x	Pulse Period		ms
d	Duty Cycle Ratio (t_p/t_x)		

Example — Find $P_{T(max)}$ (design limit)

OPERATING CONDITIONS:

$\theta_{C-HS} + \theta_{HS-A} = 2.25$ deg/W (From information supplied with heat sink.)

$T_{J(av)}$ (design limit) = 200°C

$T_A = 50^\circ\text{C}$

$d = 10\%$ (0.1)

$t_p = 0.1$ ms

Equation No. 1 — Application: d-c power dissipation, heat sink used.

$$P_{T(av)} = \frac{T_{J(av)} - T_A}{\theta_{J-C} + \theta_{C-HS} + \theta_{HS-A}} \text{ for } 25^\circ\text{C} \leq T_C \leq 200^\circ\text{C}, \text{ as in Figure 8.}$$

Equation No. 2 — Application: d-c power dissipation, no heat sink used.

$$P_{T(av)} = \frac{T_{J(av)} - T_A}{\theta_{J-A}} \text{ for } 25^\circ\text{C} \leq T_A \leq 200^\circ\text{C}$$

Equation No. 3 — Application: Peak power dissipation, heat sink used.

$$P_{T(max)} = \frac{T_{J(max)} - T_A}{d(\theta_{C-HS} + \theta_{HS-A}) + K\theta_{J-C}} \text{ for } 25^\circ\text{C} \leq T_C \leq 200^\circ\text{C}$$

Equation No. 4 — Application: Peak power dissipation, no heat sink used.

$$P_{T(max)} = \frac{T_{J(max)} - T_A}{d\theta_{C-A} + K\theta_{J-C}} \text{ for } 25^\circ\text{C} \leq T_A \leq 200^\circ\text{C}$$

Solution:

From Figure 9, Peak-Power Coefficient

$K = 0.11$ and by use of equation No. 3

$$P_{T(max)} = \frac{T_{J(max)} - T_A}{d(\theta_{C-HS} + \theta_{HS-A}) + K\theta_{J-C}}$$

$$P_{T(max)} = \frac{200 - 50}{0.1(2.25) + 0.11(1.17)} = 424 \text{ W}$$